

Octal dual supply translating transceiver; 3-state

74LVC4245A

FEATURES

- In accordance with JEDEC standard no. 8-1A
- Wide supply voltage range:
3 V port: 1.5 to 3.6 V
5 V port: 1.5 to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Control inputs accept voltages up to 5.5 V.

DESCRIPTION

The 74LVC4245A is a high-performance, low-power, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

The 74LVC4245A is an octal dual supply translating transceiver featuring non-inverting 3-state bus compatible outputs in both send and receive directions. It is designed to interface between a 3 and 5 V bus in a mixed 3/5 V supply environment.

The 74LVC4245A features an output enable (\overline{OE}) input for easy cascading and a send/receive (DIR) input for direction control. (\overline{OE}) controls the outputs so that the buses are effectively isolated.

In suspend mode, when V_{CCA} is zero, there will be no current flow from one supply to the other supply. The A-outputs must be set 3-state and the voltage on the A-bus must be smaller than V_{diode} (typ. 0.7 V). $V_{CCA} \geq V_{CCB}$ (except in suspend mode).

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25\text{ }^{\circ}\text{C}$; $t_r = t_f \leq 2.5\text{ ns}$.

| SYMBOL | PARAMETER | CONDITIONS | TYPICAL | UNIT |
|-------------------|--------------------------|----------------------------------------|---------|------|
| t_{PHL}/t_{PLH} | propagation delay | $C_L = 50\text{ pF}$ | | |
| | A_n to B_n | $V_{CCA} = 5.0\text{ V}$ | 4.0 | ns |
| | B_n to A_n | $V_{CCB} = 3.3\text{ V}$ | 4.0 | ns |
| $C_{I/O}$ | input/output capacitance | | 10.0 | pF |
| C_{PDA} | A port | | | |
| | A_n to B_n | $V_I = \text{GND to } V_{CC}$; note 1 | 7.8 | pF |
| | B_n to A_n | $V_I = \text{GND to } V_{CC}$; note 1 | 27.9 | pF |
| C_{PDB} | B port | | | |
| | A_n to B_n | $V_I = \text{GND to } V_{CC}$; note 1 | 26 | pF |
| | B_n to A_n | $V_I = \text{GND to } V_{CC}$; note 1 | 10.4 | pF |

Note

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in Volts;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

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FUNCTION TABLE

See note 1.

| INPUT | | INPUT/OUTPUT | |
|-----------------|-----|--------------|--------|
| \overline{OE} | DIR | A_n | B_n |
| L | L | A = B | inputs |
| L | H | inputs | B = A |
| H | X | Z | Z |

Note

1. H = HIGH voltage level;
L = LOW voltage level;
X = don't care;
Z = high-impedance OFF-state.

ORDERING INFORMATION

| OUTSIDE NORTH AMERICA | NORTH AMERICA | PACKAGE | | | | |
|-----------------------|---------------|-------------------|------|---------|----------|----------|
| | | TEMPERATURE RANGE | PINS | PACKAGE | MATERIAL | CODE |
| 74LVC4245AD | 74LVC4245AD | -40 to +85 °C | 24 | SO | plastic | SOT137-1 |
| 74LVC4245ADB | 74LVC4245ADB | | 24 | SSOP | plastic | SOT340-1 |
| 74LVC4245APW | 74LVC4245ADH | | 24 | TSSOP | plastic | SOT355-1 |

PINNING

| PIN | SYMBOL | DESCRIPTION |
|-----------------------------------|-----------------|----------------------------------|
| 1 | V_{CCA} | DC supply voltage (5 V bus) |
| 2 | DIR | direction control |
| 3, 4, 5, 6, 7, 8, 9 and 10 | A_0 to A_7 | data inputs/outputs |
| 11, 12 and 13 | GND | ground (0 V) |
| 14, 15, 16, 17, 18, 19, 20 and 21 | B_7 to B_0 | data inputs/outputs |
| 22 | \overline{OE} | output enable input (active LOW) |
| 23 and 24 | V_{CCB} | DC supply voltage (3 V bus) |

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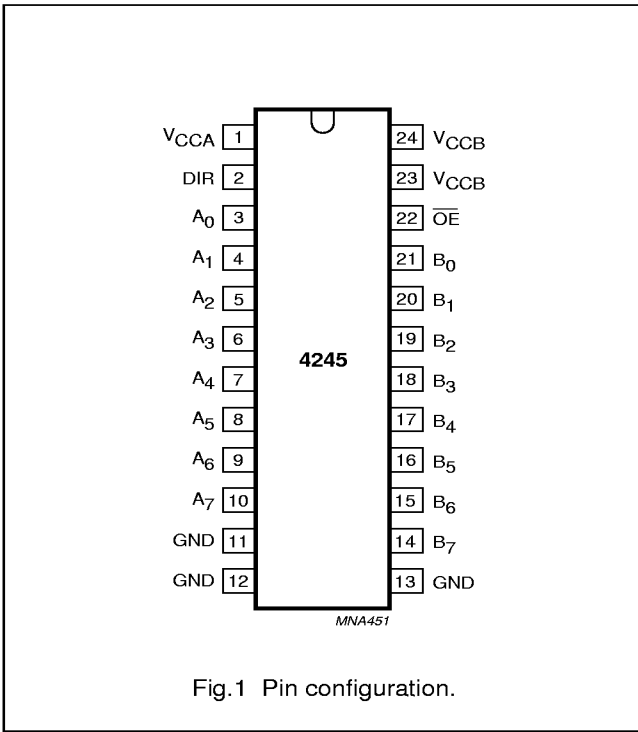


Fig.1 Pin configuration.

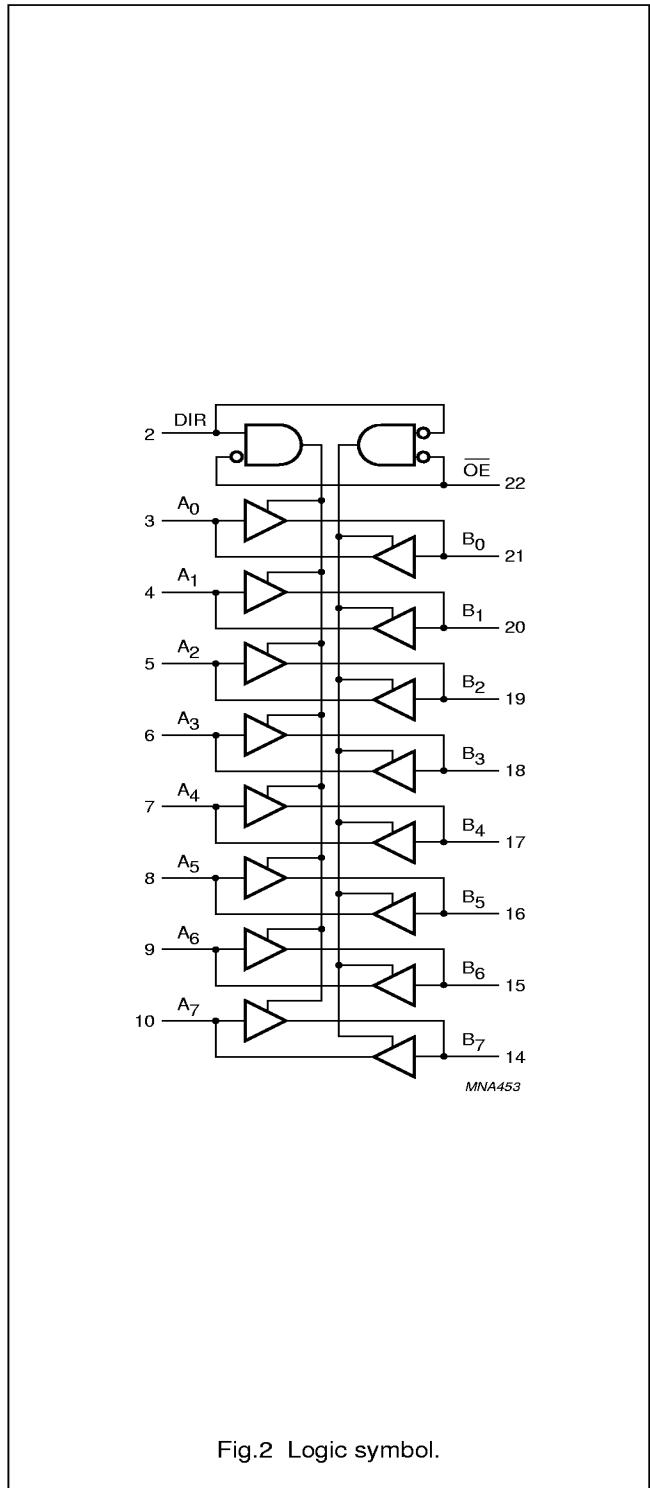


Fig.2 Logic symbol.

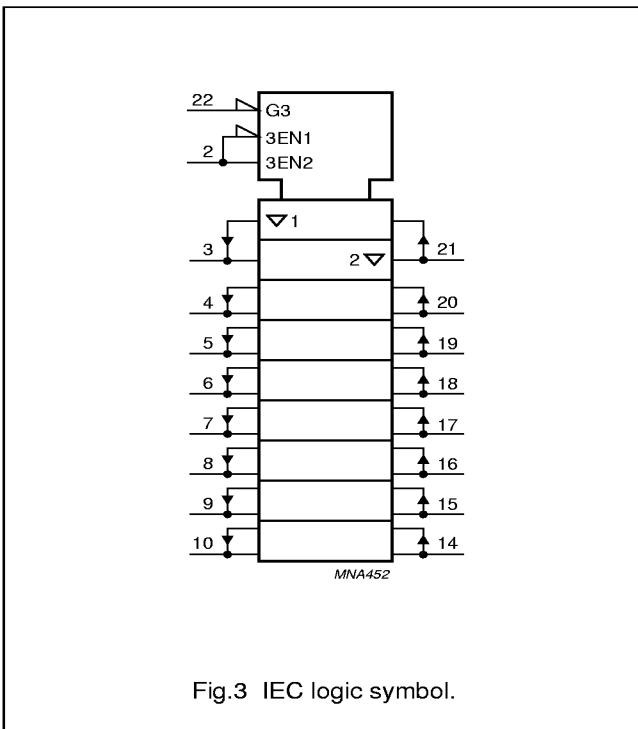


Fig.3 IEC logic symbol.

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RECOMMENDED OPERATING CONDITIONS

| SYMBOL | PARAMETER | CONDITIONS | LIMITS | | UNIT |
|---------------------------------|---------------------------------------------------------------|-------------------------------------------------|--------|-----------------|------|
| | | | MIN. | MAX. | |
| V _{CCA} | DC supply voltage 5 V port (for maximum speed performance) | V _{CCA} ≥ V _{CCB} (see Fig.5) | 1.5 | 5.5 | V |
| V _{CCB} | DC supply voltage 3 V port (for low-voltage applications) | V _{CCA} ≥ V _{CCB} (see Fig.5) | 1.5 | 3.6 | V |
| V _I | DC input voltage range (control inputs) | | 0 | 5.5 | V |
| V _{I/O} | DC input voltage range; output 3-state | | 0 | 5.5 | V |
| | DC output voltage range; output HIGH or LOW state | | 0 | V _{CC} | V |
| T _{amb} | operating ambient temperature range | see DC and AC characteristics per device | -40 | +85 | °C |
| t _r , t _f | input rise and fall times | V _{CCB} = 2.7 to 3.0 V | 0 | 20 | ns/V |
| | | V _{CCB} = 3.0 to 3.6 V | 0 | 10 | |
| | | V _{CCA} = 3.0 to 4.5 V | 0 | 20 | |
| | | V _{CCA} = 4.5 to 5.5 V | 0 | 10 | |

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0 V).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|------------------------------------|---------------------------------------------------------|--------------------------------------------------------|------|-----------------------|------|
| V _{CCA} | DC supply voltage 5 V port | | -0.5 | +6.5 | V |
| V _{CCB} | DC supply voltage 3 V port | | -0.5 | +4.6 | V |
| I _{IK} | DC input diode current | V _I < 0 | - | -50 | mA |
| V _I | DC input voltage | note 1 | -0.5 | +6.5 | V |
| I _{OK} | DC output diode current | V _O > V _{CC} or V _O < 0 | - | ±50 | mA |
| V _{I/O} | DC output voltage; output HIGH or LOW | note 1 | -0.5 | V _{CC} + 0.5 | V |
| | DC input voltage; output 3-state | note 1 | -0.5 | +6.5 | V |
| I _O | DC output diode current | V _O = 0 to V _{CC} | - | ±50 | mA |
| I _{GND} , I _{CC} | DC V _{CC} or GND current | | - | ±100 | mA |
| T _{stg} | storage temperature | | -65 | +150 | °C |
| P _{tot} | power dissipation per package plastic mini-pack (SO) | above 70 °C derate linearly with 8 mW/K | - | 500 | mW |
| | plastic shrink mini-pack (SSOP and TSSOP) | above 60 °C derate linearly with 5.5 mW/K | - | 500 | mW |

Note

- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC CHARACTERISTICS

Over recommended operating conditions; voltage are referenced to GND (ground = 0 V).

| SYMBOL | PARAMETER | TEST CONDITIONS | | T _{amb} (°C) | | | UNIT |
|------------------------------------|----------------------------------------------------------------------|--------------------------------------------------------------------------------------------------|---------------------------|-----------------------|---------------------|------|------|
| | | OTHER | V _{CCA/B} (V) | -40 to +85 | | | |
| | | | | MIN. | TYP. ⁽¹⁾ | MAX. | |
| V _{IH} | HIGH-level input voltage | 3 V port | 2.7 to 3.6 | 2.0 | – | – | V |
| | | 5 V port | 4.5 to 5.5 | 2.0 | – | – | |
| V _{IL} | LOW-level input voltage | 3 V port | 2.7 to 3.6 | – | – | 0.8 | V |
| | | 5 V port | 4.5 to 5.5 | – | – | 0.8 | |
| V _{OH} | HIGH-level output voltage (3 V port) | V _I = V _{IH} or V _{IL} ; I _O = –12 mA | 2.7 | V _{CC} – 0.5 | – | – | V |
| | | V _I = V _{IH} or V _{IL} ; I _O = –100 μA | 3.0 | V _{CC} – 0.2 | V _{CC} | – | |
| | | V _I = V _{IH} or V _{IL} ; I _O = –24 mA | 3.0 | V _{CC} – 1.0 | – | – | |
| | HIGH-level output voltage (5 V port) | V _I = V _{IH} or V _{IL} ; I _O = –12 mA | 4.5 | V _{CC} – 0.5 | – | – | V |
| | | V _I = V _{IH} or V _{IL} ; I _O = –100 μA | 4.5 | V _{CC} – 0.2 | V _{CC} | – | |
| | | V _I = V _{IH} or V _{IL} ; I _O = –24 mA | 4.5 | V _{CC} – 0.8 | – | – | |
| V _{OL} | LOW-level output voltage (3 V port) | V _I = V _{IH} or V _{IL} ; I _O = 12 mA | 2.7 | – | – | 0.40 | V |
| | | V _I = V _{IH} or V _{IL} ; I _O = 100 μA | 3.0 | – | – | 0.20 | |
| | | V _I = V _{IH} or V _{IL} ; I _O = 24 mA | 3.0 | – | – | 0.55 | |
| | LOW-level output voltage (5 V port) | V _I = V _{IH} or V _{IL} ; I _O = 12 mA | 4.5 | – | – | 0.40 | V |
| | | V _I = V _{IH} or V _{IL} ; I _O = 100 μA | 4.5 | – | – | 0.20 | |
| | | V _I = V _{IH} or V _{IL} ; I _O = 24 mA | 4.5 | – | – | 0.55 | |
| I _I | input leakage current | V _I = 5.5 V or GND; note 2 | 3.6 | – | ±0.1 | ±5 | μA |
| I _{IHZ} /I _{ILZ} | input current for common I/O pins (3 V port) | V _I = V _{CC} or GND | 3.6 | – | 0.1 | ±15 | μA |
| | input current for common I/O pins (5 V port) | V _I = V _{CC} or GND | 5.5 | – | 0.1 | ±15 | μA |
| I _{OZ} | 3-state output OFF-state current (3 V port) | V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND | 3.6 | – | 0.1 | ±5 | μA |
| | 3-state output OFF-state current (5 V port) | V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND | 5.5 | – | 0.1 | ±5 | μA |
| I _{CC} | quiescent supply current (3 V port) | V _I = V _{CC} or GND; I _O = 0 | 3.6 | – | 0.1 | 10 | μA |
| | quiescent supply current (5 V port) | V _I = V _{CC} or GND; I _O = 0 | 5.5 | – | 0.1 | 10 | μA |
| ΔI _{CC} | additional quiescent supply current per control pin (3 V port) | V _I = V _{CC} – 0.6 V; I _O = 0 | 2.7 to 3.6 | – | 5 | 500 | μA |
| | additional quiescent supply current per control pin (5 V port) | V _I = V _{CC} – 2.1 V; I _O = 0 | 4.5 to 5.5 | – | 5 | 500 | μA |

Notes

1. All typical values are at V_{CCA} = 5.0 V, V_{CCB} = 3.3 V and T_{amb} = 25 °C.
2. Not for I/O pins.

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AC CHARACTERISTICS

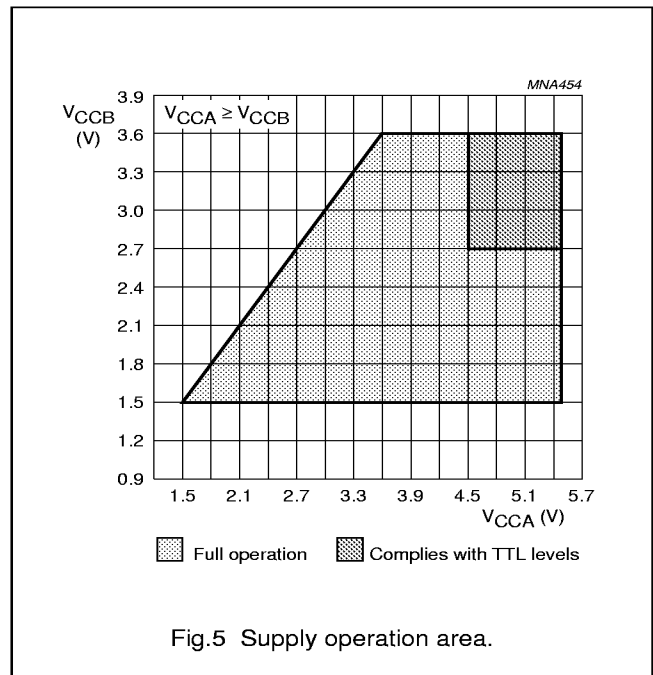
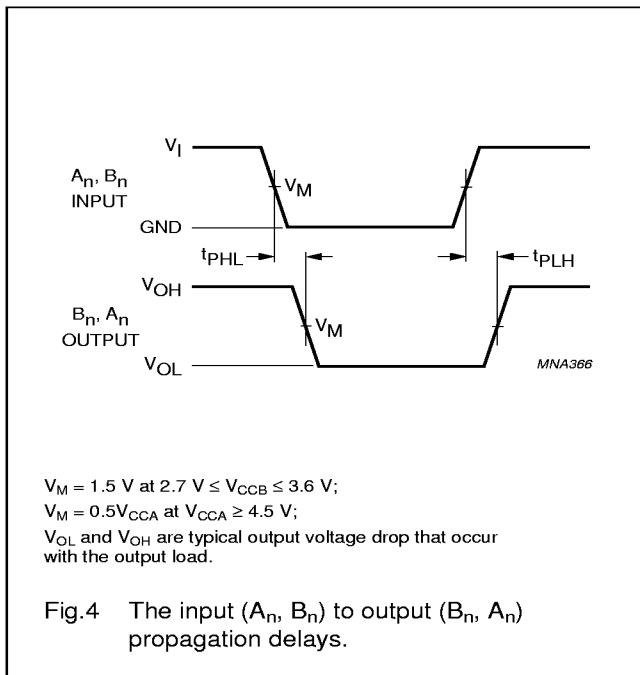
GND = 0 V; $t_r = t_f \leq 2.5$ ns; $C_L = 50$ pF; $T_{amb} = -40$ to 85 °C.

| SYMBOL | PARAMETER | WAVEFORMS | LIMITS | | | | | | UNIT |
|-------------------|------------------------------------------------------|------------------|-------------------------------------------|---------|------|--------------------------|---------|------|------|
| | | | $V_{CCA} = 5\text{ V} \pm 0.5\text{ V}$ | | | | | | |
| | | | $V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$ | | | $V_{CCB} = 2.7\text{ V}$ | | | |
| | | | MIN. | TYP.(1) | MAX. | MIN. | TYP.(2) | MAX. | |
| t_{PHL}/t_{PLH} | propagation delay A_n to B_n | see Figs 4 and 7 | 1.5 | 4.0 | 6.5 | 1.5 | 4.5 | 7.0 | ns |
| | propagation delay B_n to A_n | see Figs 4 and 7 | 1.5 | 4.0 | 6.5 | 1.5 | 4.5 | 7.0 | ns |
| t_{PZH}/t_{PZL} | 3-state output enable time \overline{OE} to A_n | see Figs 6 and 7 | 1.5 | 6.2 | 10 | 1.5 | 7.0 | 11.0 | ns |
| | 3-state output enable time \overline{OE} to B_n | see Figs 6 and 7 | 1.5 | 5.0 | 8.1 | 1.5 | 5.7 | 8.7 | ns |
| t_{PHZ}/t_{PLZ} | 3-state output disable time \overline{OE} to A_n | see Figs 6 and 7 | 1.5 | 5.3 | 7.5 | 1.5 | 5.7 | 8.0 | ns |
| | 3-state output disable time \overline{OE} to B_n | see Figs 6 and 7 | 1.5 | 5.8 | 7.8 | 1.5 | 6.2 | 8.5 | ns |

Notes

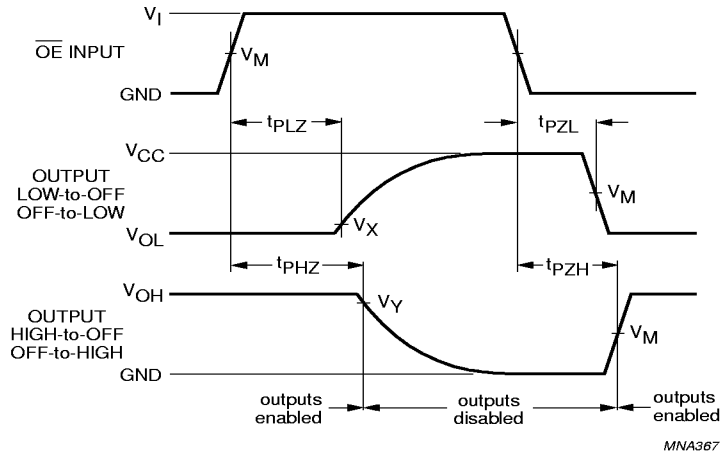
1. Typical values are measured at $V_{CCA} = 5.0$ V and $V_{CCB} = 3.3$ V and $T_{amb} = 25$ °C.
2. Typical values are measured at $V_{CCA} = 5.0$ V and $T_{amb} = 25$ °C.

AC WAVEFORMS



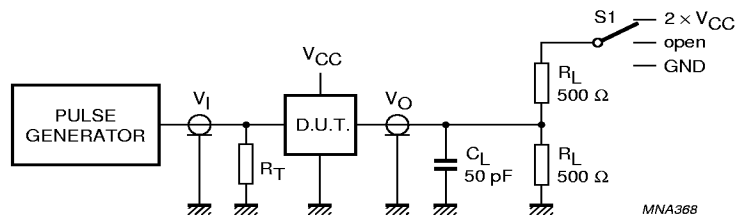
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$V_M = 1.5 \text{ V}$ at $2.7 \text{ V} \leq V_{CCB} \leq 3.6 \text{ V}$;
 $V_M = 0.5V_{CCA}$ at $V_{CCA} \geq 4.5 \text{ V}$;
 $V_X = V_{OL} + 0.3 \text{ V}$ at $V_{CCB} \leq 3.6 \text{ V}$;
 $V_X = V_{OL} + 0.1 (V_{CCA} - V_{OL})$ at $V_{CCA} \geq 4.5 \text{ V}$;
 $V_Y = V_{OH} - 0.3 \text{ V}$ at $V_{CCB} \leq 3.6 \text{ V}$;
 $V_Y = V_{OH} - 0.1 (V_{OH} - \text{GND})$ at $V_{CCA} \geq 4.5 \text{ V}$;
 V_{OL} and V_{OH} are typical output voltage drop that occur with the output load.

Fig.6 The 3-state enable and disable times.



| TEST | S ₁ | V _{CC} | V _I |
|------------------------------------|---------------------|----------------------------|-----------------|
| t _{PLH} /t _{PHL} | open | for A and B port <2.7 V | V _{CC} |
| t _{PLZ} /t _{PZL} | 2 × V _{CC} | for B port 2.7 to 3.6 V | 2.7 V |
| t _{PHZ} /t _{PZH} | GND | for A port 4.5 to 5.5 V | 3.0 V |

Definitions for test circuit:
 R_L = Load resistor; see chapter "AC characteristics".
 C_L = Load capacitance including jig and probe capacitance (see chapter "AC characteristics").
 R_T = Termination resistance should be equal to the output impedance Z_0 of the pulse generator.

Fig.7 Load circuitry for switching times.

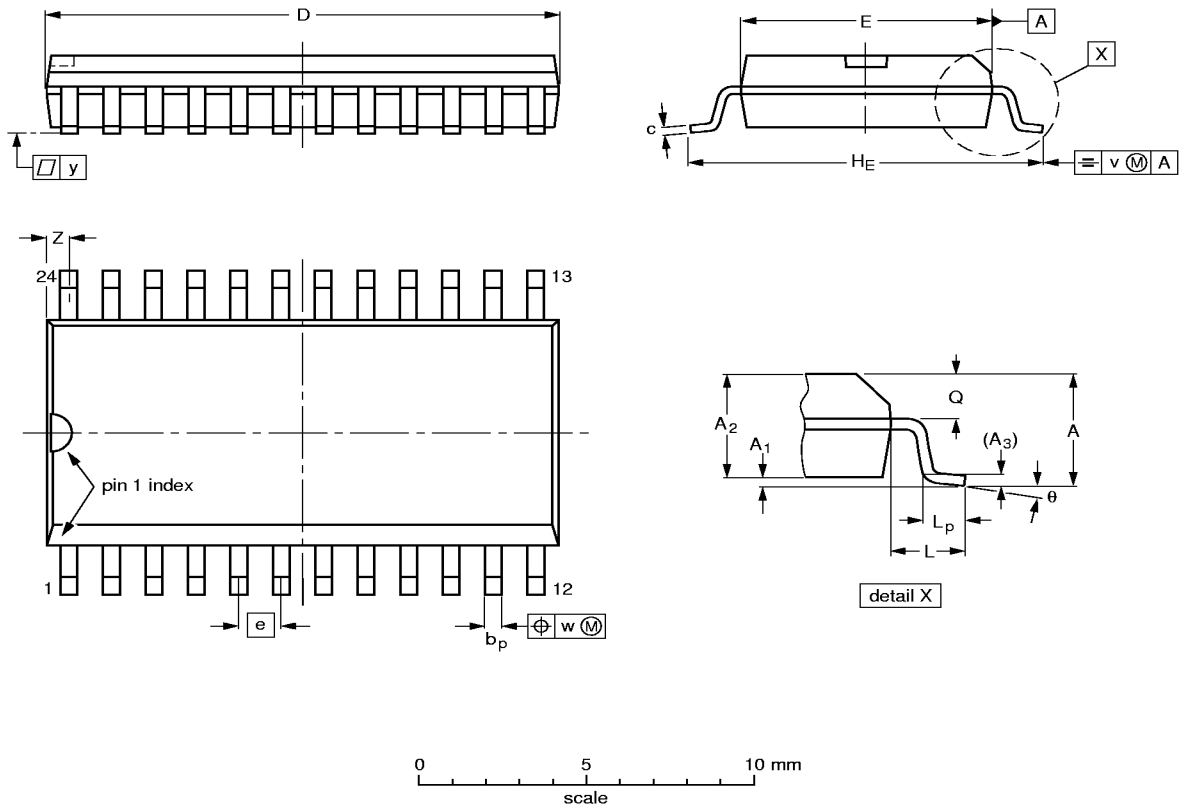
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PACKAGE OUTLINES

SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

| UNIT | A max. | A ₁ | A ₂ | A ₃ | b _p | c | D ⁽¹⁾ | E ⁽¹⁾ | e | H _E | L | L _p | Q | v | w | y | Z ⁽¹⁾ | θ |
|--------|--------|----------------|----------------|----------------|----------------|----------------|------------------|------------------|-------|----------------|-------|----------------|----------------|------|------|-------|------------------|----------|
| mm | 2.65 | 0.30 0.10 | 2.45 2.25 | 0.25 | 0.49 0.36 | 0.32 0.23 | 15.6 15.2 | 7.6 7.4 | 1.27 | 10.65 10.00 | 1.4 | 1.1 0.4 | 1.1 1.0 | 0.25 | 0.25 | 0.1 | 0.9 0.4 | 8° 0° |
| inches | 0.10 | 0.012 0.004 | 0.096 0.089 | 0.01 | 0.019 0.014 | 0.013 0.009 | 0.61 0.60 | 0.30 0.29 | 0.050 | 0.419 0.394 | 0.055 | 0.043 0.016 | 0.043 0.039 | 0.01 | 0.01 | 0.004 | 0.035 0.016 | |

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

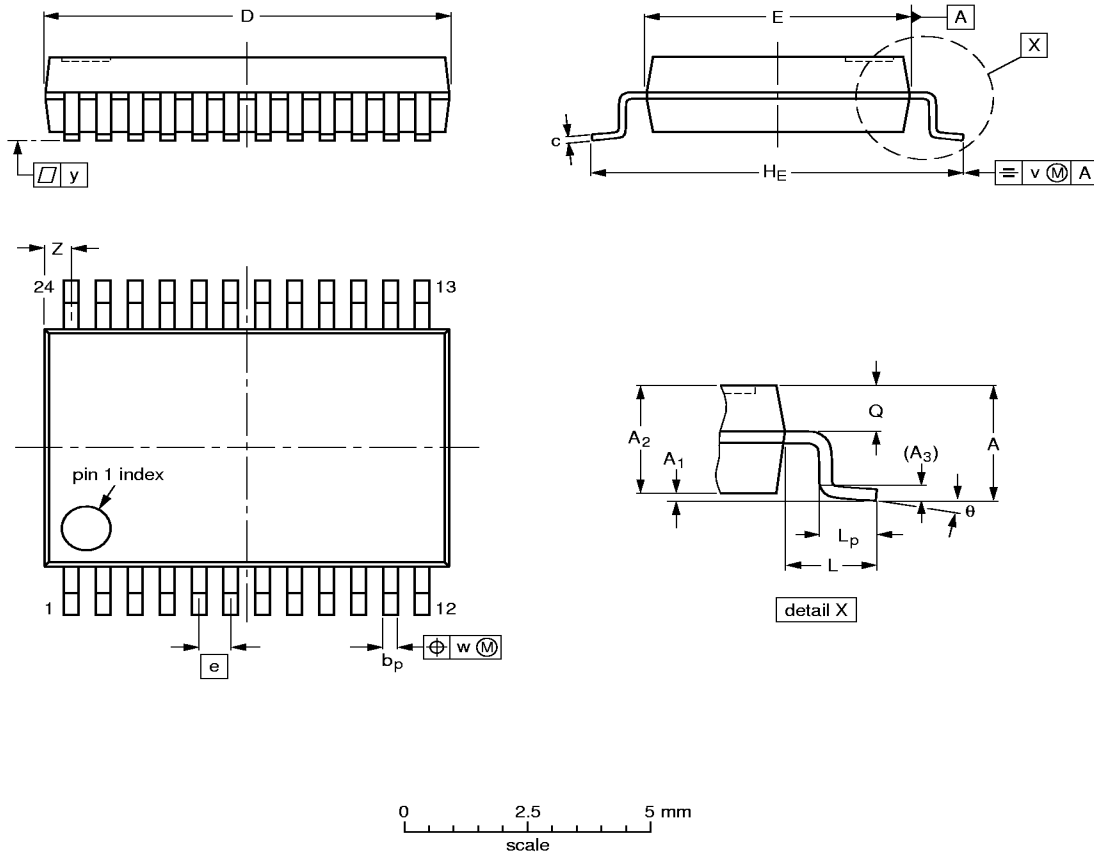
| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|----------|------|--|---------------------|-----------------------|
| | IEC | JEDEC | EIAJ | | | |
| SOT137-1 | 075E05 | MS-013AD | | | | -95-01-24 97-05-22 |

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SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1



DIMENSIONS (mm are the original dimensions)

| UNIT | A max. | A ₁ | A ₂ | A ₃ | b _p | c | D ⁽¹⁾ | E ⁽¹⁾ | e | H _E | L | L _p | Q | v | w | y | Z ⁽¹⁾ | θ |
|------|--------|----------------|----------------|----------------|----------------|--------------|------------------|------------------|------|----------------|------|----------------|------------|-----|------|-----|------------------|----------|
| mm | 2.0 | 0.21 0.05 | 1.80 1.65 | 0.25 | 0.38 0.25 | 0.20 0.09 | 8.4 8.0 | 5.4 5.2 | 0.65 | 7.9 7.6 | 1.25 | 1.03 0.63 | 0.9 0.7 | 0.2 | 0.13 | 0.1 | 0.8 0.4 | 8° 0° |

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

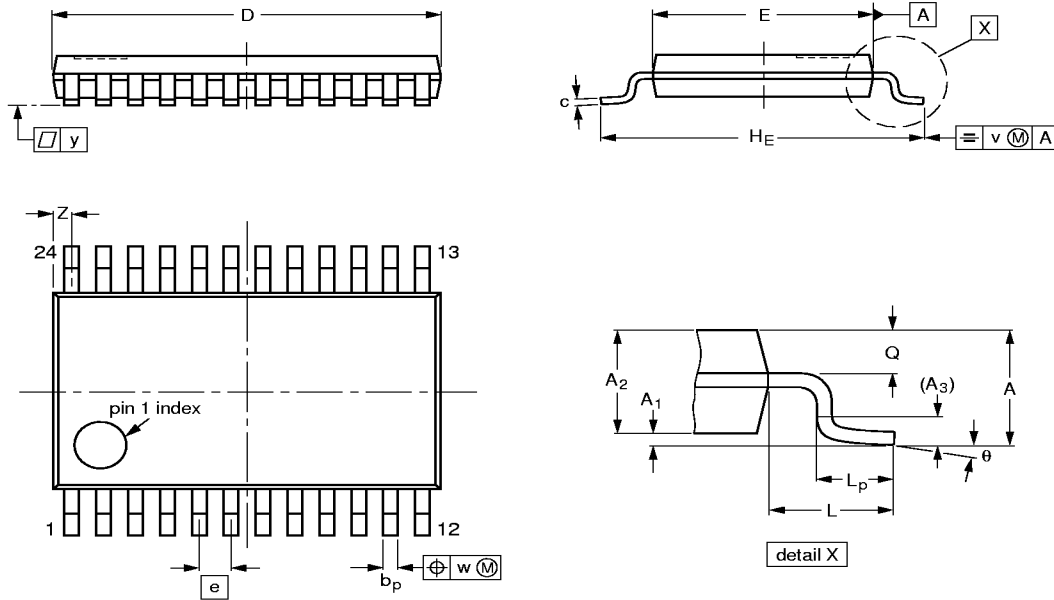
| OUTLINE VERSION | REFERENCES | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|----------|------|---------------------|----------------------|
| | IEC | JEDEC | EIAJ | | |
| SOT340-1 | | MO-150AG | | | 93-09-08 95-02-04 |

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TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1



DIMENSIONS (mm are the original dimensions)

| UNIT | A max. | A ₁ | A ₂ | A ₃ | b _p | c | D ⁽¹⁾ | E ⁽²⁾ | e | H _E | L | L _p | Q | v | w | y | Z ⁽¹⁾ | θ |
|------|--------|----------------|----------------|----------------|----------------|------------|------------------|------------------|------|----------------|-----|----------------|------------|-----|------|-----|------------------|----------|
| mm | 1.10 | 0.15 0.05 | 0.95 0.80 | 0.25 | 0.30 0.19 | 0.2 0.1 | 7.9 7.7 | 4.5 4.3 | 0.65 | 6.6 6.2 | 1.0 | 0.75 0.50 | 0.4 0.3 | 0.2 | 0.13 | 0.1 | 0.5 0.2 | 8° 0° |

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES | | | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|----------|------|---------------------|----------------------|
| | IEC | JEDEC | EIAJ | | |
| SOT355-1 | | MO-153AD | | | 93-06-16 95-02-04 |

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SOLDERING

Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "Data Handbook IC26; Integrated Circuit Packages" (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering is not always suitable for surface mount ICs, or for printed-circuit boards with high population densities. In these situations reflow soldering is often used.

Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, infrared/convection heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferably be kept below 230 °C.

Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
 - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
 - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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Suitability of surface mount IC packages for wave and reflow soldering methods

| PACKAGE | SOLDERING METHOD | |
|-------------------------------|-----------------------------------|-----------------------|
| | WAVE | REFLOW ⁽¹⁾ |
| BGA, SQFP | not suitable | suitable |
| HLQFP, HSQFP, HSOP, SMS | not suitable ⁽²⁾ | suitable |
| PLCC ⁽³⁾ , SO, SOJ | suitable | suitable |
| LQFP, QFP, TQFP | not recommended ⁽³⁾⁽⁴⁾ | suitable |
| SSOP, TSSOP, VSO | not recommended ⁽⁵⁾ | suitable |

Notes

1. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the "Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods".
2. These packages are not suitable for wave soldering as a solder joint between the printed-circuit board and heatsink (at bottom version) can not be achieved, and as solder may stick to the heatsink (on top version).
3. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
4. Wave soldering is only suitable for LQFP, TQFP and QFP packages with a pitch (e) equal to or larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
5. Wave soldering is only suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

DEFINITIONS

| Data sheet status | |
|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------|
| Objective specification | This data sheet contains target or goal specifications for product development. |
| Preliminary specification | This data sheet contains preliminary data; supplementary data may be published later. |
| Product specification | This data sheet contains final product specifications. |
| Limiting values | |
| Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability. | |
| Application information | |
| Where application information is given, it is advisory and does not form part of the specification. | |

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.